

FOR: BE SEMICONDUCTOR INDUSTRIES N.V.

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6921 RW Duiven The Netherlands

BE Semiconductor Industries Announces Management Board Change

Duiven, the Netherlands, September 1, 2009, BE Semiconductor Industries N.V. ("Besi") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced that Mr Helmut R. Rutterschmidt has decided not to renew his contract with the Company which expires at year end 2009 and will consequently resign from his position as Management Board Member of Besi and President and Chief Executive Officer of Datacon Technology GmbH effective September 1, 2009. Mr Rutterschmidt resigned to pursue personal interests outside the semiconductor assembly equipment industry. His responsibilities will be assumed by Richard W. Blickman, Chief Executive Officer of Besi.

About BE Semiconductor Industries N.V.

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, wire bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European, Asian, Korean and Japanese semiconductor manufacturers and subcontractors which utilize its products for both array connect and conventional leadframe manufacturing processes.

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